

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	N/A	Silicon Carbide (SiC)	409-21-2	0.01762	100.0	1.29
Subtotal				0.01762	100	1.29
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.04646	100.0	3.402
Subtotal				0.04646	100	3.402
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.02042	65.0	1.495
	Lead alloy	Silver (Ag)	7440-22-4	0.00785	25.0	0.575
	Lead alloy	Antimony (Sb)	7440-36-0	0.00314	10.0	0.23
	Subtotal				0.03141	100
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.01989	0.03	1.4568
	Copper alloy	Iron (Fe)	7439-89-6	0.06631	0.1	4.856
	Copper alloy	Copper (Cu)	7440-50-8	66.22549	99.87	4,849.6872
	Subtotal				66.31169	100
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	1.32733	4.0	97.2
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	4.97747	15.0	364.5
	Filler	Silica fused	60676-86-0	24.55554	74.0	1,798.2
	Flame retardant	Metal hydroxide		2.32282	7.0	170.1
	Subtotal				33.18316	100
Post-plating	Pure metal	Tin (Sn)	7440-31-5	0.40967	100.0	30
Subtotal				0.40967	100	30
Total				100.00001	100	NaN

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